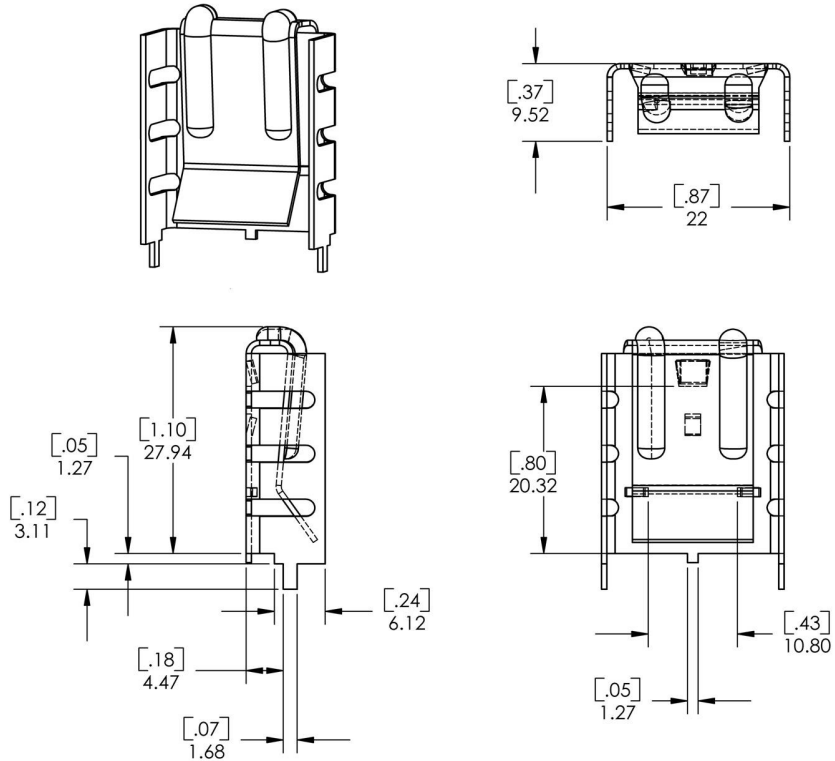
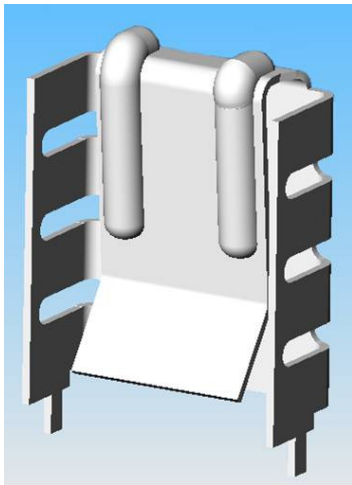


# Board Level Heat Sinks



ThermaFlo

P/N: 833702T00000



## PRODUCT SPECIFICATIONS

- Devices: TO-220
- Size: 9.5 x 22.0 x 28.0mm
- Material: Copper, 0.6mm thick
- Type: Stamped
- Finish: Tin Plate
- PCB Mounting: Solderable Tabs
- IC Mounting: Integrated Spring
- Package: Bulk

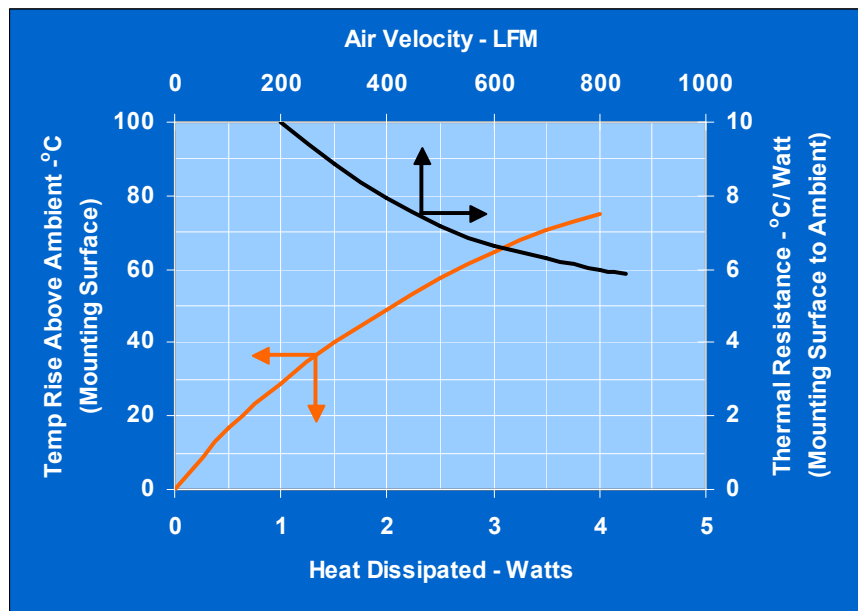
## FEATURES & BENEFITS

- No Hardware Device Attachment
- Constant Spring Force Tension
- RoHS Compliant



## CUSTOMIZED HEATSINKS

- Specialized Tabs, Plating
- Specialized Body Configurations
- Contact Applications Engineering



TO-220

**COMAIR ROTRON, INC**  
 8929 Terman Court, San Diego, CA 92121  
 Ph (858) 348-6200 Fax (858) 566-4577  
 E-mail: sales@comairrotron.com,  
 Web: www.comairrotron.com